

VIA FACSIMILE TRANSMISSION 1-571-273-8300

PATENT
Atty. Docket No. 17938 (AT 20958-02091)

IN THE SPECIFICATION:

Please replace paragraph [0020] with the following replacement paragraph:

[0020] The base portions 18 and 19 of the contact elements 10 and 14 are soldered to a common pad 9 or electrically joined traces on a circuit board ~~(not shown)~~ 7. A processor (which is then positioned on a socket containing the contact elements 10 and 14), has one or more electrically common contact pads on the bottom surface of the processor that engage the contact portions 50 of the contact elements 10 and 14. The weight of the processor pushes the contact beams 34 of the contact element 10 downward along arrow A, and the contact beams 38 of the contact element 14 downward along arrow B. The contact beams 34 and 38 of the contact elements 10 and 14 may be deflected downward, for example, until aligned in a common plane, as well as parallel with each other and with the longitudinal axis 54.

Please replace paragraph [0021] with the following replacement paragraph:

In operation, electrical current travels through the contact elements 10 and 14 between the circuit board 7 and the processor. When signals are conveyed from the circuit board 7 to the processor, the current flows in the direction of arrow C from the base portion 18 to the contact portions 50 of the contact beams 34. In the contact element 14, the current flows in the direction of arrows D from the base portion 19 to the contact portions 50 of the contact beams 38. As current travels through the contact elements 10 and 14, electromagnetic (EM) fields are created about the corresponding contact beams 34 and 38. However, because the contact beams 34 and 38 of the contact elements 10 and 14 are interleaved and overlap along the transverse axis 42 and face one another, adjacent contact beams 34 and 38 carry current in opposite directions.

Please replace paragraph [0023] with the following replacement paragraph:

As noted above, multiple contact elements 10 and 14 are joined to one or more electrically common pads 9 or traces on the circuit board 7 at a plurality of solder ball paddles 22 and 23. Hence, all of the contact beams 34 and 38 in the contact 8 operate in parallel. This parallel operation enables each individual contact beam 34 and 38 to be small, while the contact

VIA FACSIMILE TRANSMISSION 1-571-273-8300

PATENT
Atty. Docket No. 17938 (AT 20958-02091)

beams 34 and 38 of a single contact 8 collectively operate to afford a low resistance connection between the processor and circuit board. Therefore, electrical signals encounter less resistance when traveling through the contact 8 and create less heat and require less energy.